L Number	Hits	Search Text	DB	Time stamp
1	1242	("235/492").CCLS.	USPAT;	2001/11/16 15:33
			US-PGPUB	
3	146	gem\$1plus.as.	USPAT;	2001/11/16 15:01
			US-PGPUB	
4	112	gem\$1plus.as. not (("235/492").CCLS.)	USPAT;	2001/11/16 15:26
5	47	mini adj2 card	US-PGPUB	2001/11/16 15:20
3	7/		USPAT; US-PGPUB	2001/11/16 15:30
6	5311	card same substrate\$1	USPAT;	2001/11/16 15:33
			US-PGPUB	
7	389990	mold\$4	USPAT;	2001/11/16 15:30
			US-PGPUB	
9	24	(card same substrate\$1) same mold\$4 and (("235/492").CCLS.)	USPAT;	2001/11/16 15:31
40	252	(11275 (4071)) 661 6	US-PGPUB	
10	352	("235/492").CCLS.	EPO; JPO;	2001/11/16 15:33
			DERWENT; IBM TDB	
11	6109	card same substrate\$1	EPO; JPO;	2001/11/16 15:34
			DERWENT;	
			IBM TDB	
12	18	(("235/492").CCLS.) and (card same substrate\$1)	EPO; JPO;	2001/11/16 15:36
			DERWENT;	
4.5	427	(HDDE (444H) CCI C	IBM TDB	2004/44/45 45 44
13	427	("235/441").CCLS.	USPAT; US-PGPUB	2001/11/16 15:41
14	21	"mini card"	EPO; JPO;	2001/11/16 15:41
-			DERWENT:	2001/11/10 15.11
			IBM TDB	
15	24	hitachi.in.	USPAT;	2001/11/16 15:45
	40000		US-PGPUB	
16	10090	(chip ic (integrated adj1 circuit) smart) adj2 card	USPAT;	2001/11/16 16:00
17	321	mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2	US-PGPUB USPAT;	2001/11/16 15:52
	721	card)	US-PGPUB	. 2001/11/10 13.32
21	100	(mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2	USPAT;	2001/11/16 15:53
		card)) and substrate\$1	US-PGPUB	
22	60	((mold\$4 same ((chip ic (integrated adj1 circuit) smart) adj2	USPAT;	2001/11/16 15:54
77	77777	card)) and substrate\$1) and memory	US-PGPUB	2001/14/15 15 5:
,23	27222	(chip ic (integrated adj1 circuit) smart) adj2 card	EPO; JPO;	2001/11/16 16:01
			DERWENT; IBM TDB	
24	401	((chip ic (integrated adj1 circuit) smart) adj2 card) same	EPO; JPO;	2001/11/16 16:01
- '	.52	mold\$4	DERWENT;	
			IBM TDB	
26	2	((((chip ic (integrated adj1 circuit) smart) adj2 card) same	EPO; JPO;	2001/11/16 16:01
		mold\$4) same substrate\$1) and memory	DERWENT;	
25	93	(((chip ic (integrated adj1 circuit) smart) adj2 card) same	IBM TDB	2001/11/16 16:03
ر ح	93	mold\$4) same substrate\$1	EPO; JPO; DERWENT;	2001/11/16 16:02
		more is come addantice.	IBM TDB	